Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.014”**

**.003”**

**.009”**

**Top Material: Al**

**Backside Material: AuAs**

**Bond Pad Size = .003 x .003”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .014” X .014” DATE: 1/30/23**

**MFG: SILICON SUPPLIES THICKNESS .009” P/N: 1N3600**

**DG 10.1.2**

#### Rev B, 7/1